ABSTRACT

The present invention provides a laser processing method for forming a recess and/or a through-hole in a workpiece using a laser, the laser processing method including: irradiating the workpiece with a laser having an optical axis inclined with respect to a normal of a workpiece surface of the workpiece; and performing laser processing while rotating the optical axis of the laser around the normal of the workpiece surface as a rotation axis to form a recess and/or a through-hole in the workpiece. According to this, formation of a tapered recess and/or a tapered through-hole can be prevented even when the recess and/or the through-hole is formed with high resolution, and thus a high-resolution and complex pattern can be formed.